

**High-temp.-resistant hot-melt adhesive**

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**Abstract of CN1401724**

A high-temp.-resistant hot-melt adhesive for electronic device is prepared from polyamide (55-70 wt.%), EVA (0-5 wt.%), rosin (7.5-10 wt.%), glyceride (7.5-10 wt.%), nano-Al<sub>2</sub>O<sub>3</sub> (12-15 wt.%), nano zinc oxide (3-5 wt.%) and nano magnesium oxide (0-3 wt.%). Its advantages are high working temp (130-150 deg.C) and no odour release.

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